



Material Content Data Sheet



Sales Product Name		IPLU300N04S4-R8		Issued		2. August 2018		
MA#		MA001614948						
Package		PG-HSOF-8-1		Weight*		768.59 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.174	0.02		227	
	noble metal	gold	7440-57-5	0.676	0.09		880	
	inorganic material	silicon	7440-21-3	6.482	0.84	0.95	8434	9541
leadframe	inorganic material	phosphorus	7723-14-0	0.126	0.02		164	
	non noble metal	iron	7439-89-6	0.421	0.05		547	
	non noble metal	copper	7440-50-8	420.040	54.65	54.72	546506	547217
wire	non noble metal	aluminium	7429-90-5	14.731	1.92	1.92	19166	19166
encapsulation	organic material	carbon black	1333-86-4	4.784	0.62		6224	
	plastics	epoxy resin	-	52.624	6.85		68468	
	inorganic material	silicondioxide	60676-86-0	261.527	34.03	41.50	340268	414960
leadfinish	non noble metal	tin	7440-31-5	6.479	0.84	0.84	8430	8430
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		2	
	non noble metal	nickel	7440-02-0	0.526	0.07	0.07	684	686
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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